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#266
7-12-01
Jetro-

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF: :
Masashi GOTOH, et al. : EXAMINER: CUNEO, K.
SERIAL NO.: 09/119,626 :
CPA FILED: January 29, 2001 : GROUP ART UNIT: 2841
FOR: CIRCUIT BOARD HAVING :
BONDING AREAS TO BE
JOINED WITH BUMPS BY
ULTRASONIC BONDING

RECEIVED
JUL 12 2001
TECHNOLOGY CENTER 2800

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Official Action dated March 13, 2001, please amend the above-identified application as follows:

IN THE CLAIMS

Claim 13 is amended as follows:

13. (Once Amended) A circuit board comprising:
a main body; and
a conductive layer provided on said main body, said conductive layer having
conductive pattern, said conductive pattern having:
a plurality of bonding areas to where a plurality of bumps of a chip
element are simultaneously joined by ultrasonic bonding; and